

英飞凌汽车级100V 175°C N沟道
增强型OptiMOS™ 5 功率晶体管

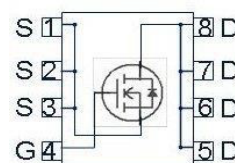
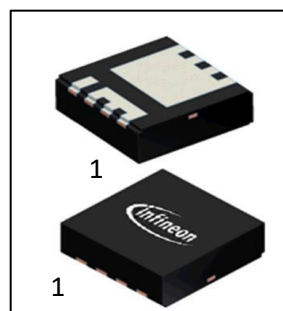
特点

- 适用于汽车应用的功率MOSFET
- N 沟道 - 增强型 - 逻辑电平
- 通过 AEC-Q101 认证
- MSL1 回流焊峰值温度高达 260°C
- 工作温度 175°C
- 绿色产品：符合 RoHS 标准
- 100% 雪崩测试
- 可进行自动光学检测 (AOI)

Type	Package	Marking
IAUZ30N10S5L240	PG-TSDSON-8	5N1L240

产品概述

V_{DS}	100	V
$R_{DS(on),max}$	24	mΩ
I_D	30	A

PG-TSDSON-8


除非另有规定，否则均为 $T_J=25^\circ\text{C}$ 的**最大额定值**。

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_C=25^\circ\text{C}, V_{GS}=10\text{V}$	30	A
		$T_C=100^\circ\text{C}, V_{GS}=10\text{V}^{(1)}$	22	
Pulsed drain current ⁽¹⁾	$I_{D,pulse}$	$T_C=25^\circ\text{C}$	120	
Avalanche energy, single pulse ⁽¹⁾	E_{AS}	$I_D=12\text{A}$	17	mJ
Avalanche current, single pulse	I_{AS}	-	12	A
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	$T_C=25^\circ\text{C } T_J=175^\circ\text{C}$	45.5	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	-

本数据手册的原文使用英文撰写。为方便起见，英飞凌提供了译文；由于翻译过程中可能使用了自动化工具，英飞凌不保证译文的准确性。为确认准确性，请务必访问 infineon.com 参考最新的英文版本（控制文档）。

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

热特性¹⁾

Thermal resistance, junction - case	R_{thJC}	-	-	-	3.3	K/W
Thermal resistance, junction - ambient	R_{thJA}	6 cm ² cooling area ²⁾	-	-	62	

除非另有规定，否则均为 $T_j=25^{\circ}\text{C}$ 的电气特性。

静态参数特性

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=1mA$	100	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=15\mu A$	1.2	1.7	2.2	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V, T_j=25^{\circ}\text{C}$	-	-	1	μA
		$V_{DS}=100V, V_{GS}=0V, T_j=125^{\circ}\text{C}^{1)}$	-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=15A$	-	26	31	m Ω
		$V_{GS}=10V, I_D=15A$	-	19.5	24	
Gate resistance ¹⁾	R_G		-	1.5	-	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

动态参数特性¹⁾

Input capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=50V,$ $f=1MHz$	-	640	832	pF
Output capacitance	C_{oss}		-	113	147	
Reverse transfer capacitance	C_{rss}		-	7.9	11.8	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50V, V_{GS}=10V,$ $I_D=30A, R_G=3.5 \Omega$	-	2	-	ns
Rise time	t_r		-	1	-	
Turn-off delay time	$t_{d(off)}$		-	4.6	-	
Fall time	t_f		-	3.4	-	

门极电荷特点¹⁾

Gate to source charge	Q_{gs}	$V_{DD}=50V, I_D=15A,$ $V_{GS}=0 \text{ to } 10V$	-	2.1	2.7	nC
Gate to drain charge	Q_{gd}		-	1.9	2.9	
Gate charge total	Q_g		-	9.5	14	
Gate plateau voltage	$V_{plateau}$		-	3.3	-	V

反向二极管

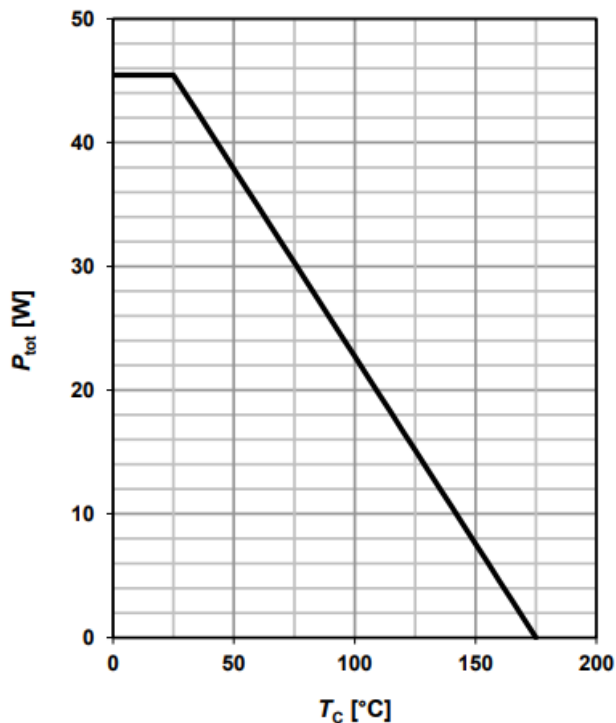
Diode continuous forward current ¹⁾	I_S	$T_C=25^\circ C$	-	-	30	A
Diode pulse current ¹⁾	$I_{S,pulse}$		-	-	120	
Diode forward voltage	V_{SD}	$V_{GS}=0V, I_F=15A,$ $T_J=25^\circ C$	-	0.9	1.1	V
Reverse recovery time ¹⁾	t_{rr}	$V_R=50V, I_F=30A,$ $di_F/dt=100A/\mu s$	-	37	-	ns
Reverse recovery charge ¹⁾	Q_{rr}		-	34	-	nC

¹⁾由设计标定，不受制于生产测试。

²⁾在 40 mm x 40 mm x 1.5 mm 环氧树脂印刷电路板 FR4 上器件，具有 6 cm²（一层，70 μm 厚）铜区域用于漏极连接。印刷电路板在静止空气中是垂直的。

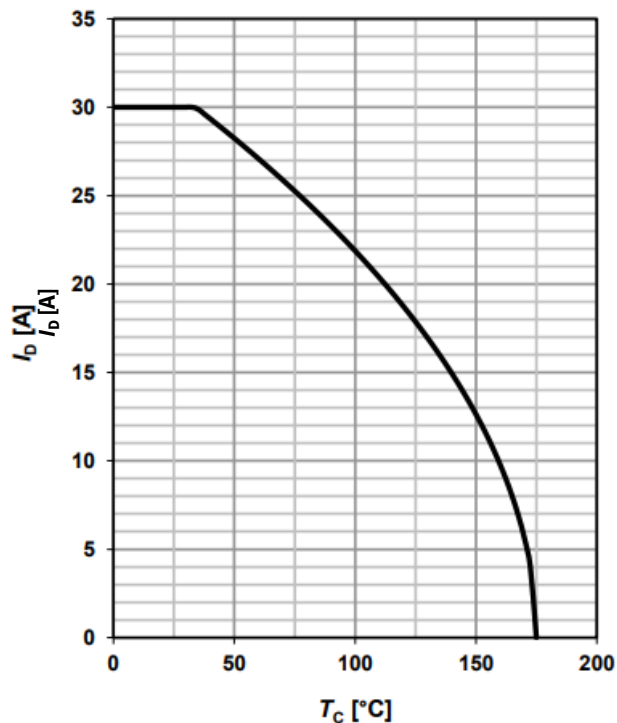
1 功率耗散

$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



2 漏极电流

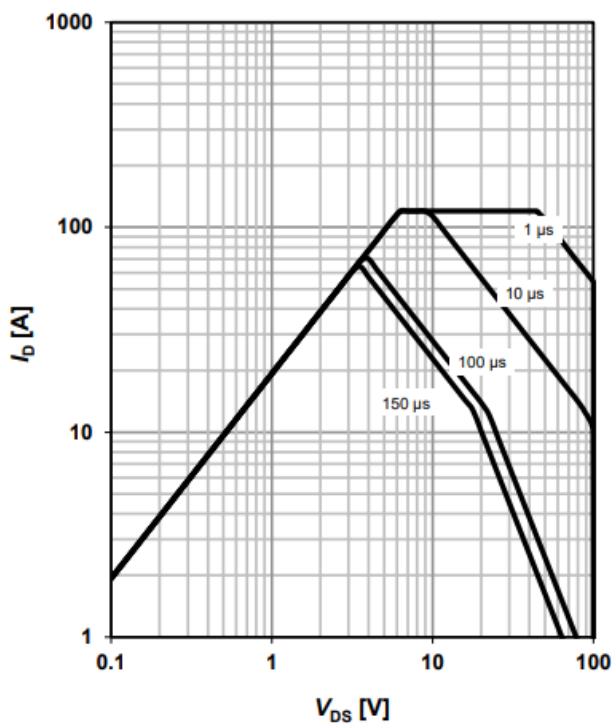
$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



3 安全工作区

$$I_D = f(V_{\text{DS}}); T_C = 25^\circ\text{C}; D = 0$$

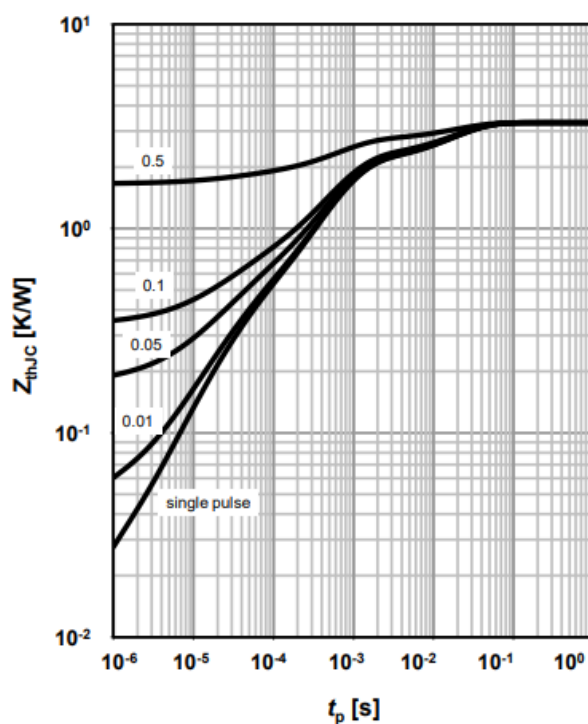
parameter: t_p



4 最大瞬态热阻抗

$$Z_{\text{thJC}} = f(t_p)$$

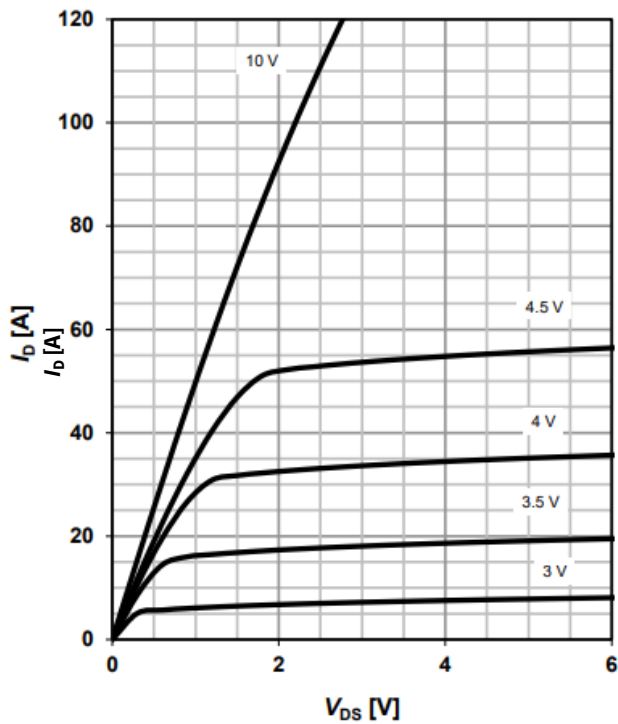
parameter: $D = t_p/T$



5 典型输出特性

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

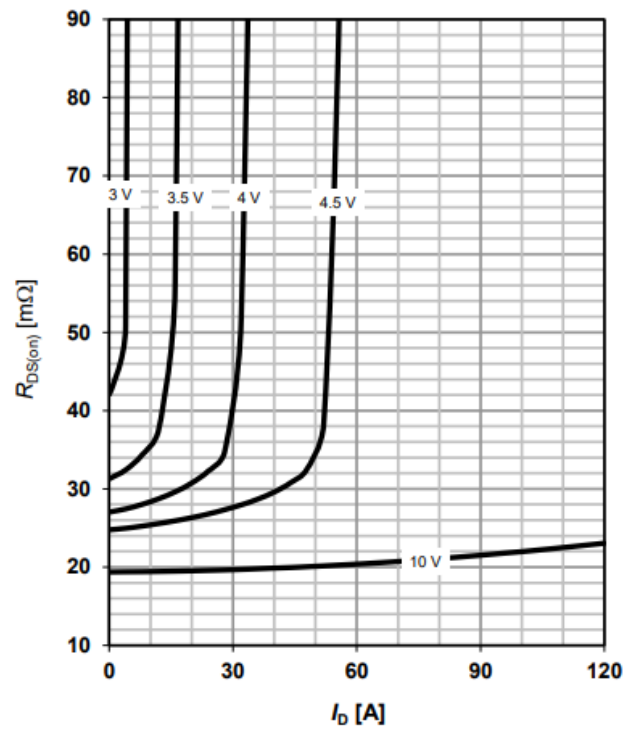
parameter: V_{GS}



6 典型漏源导通电阻

$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

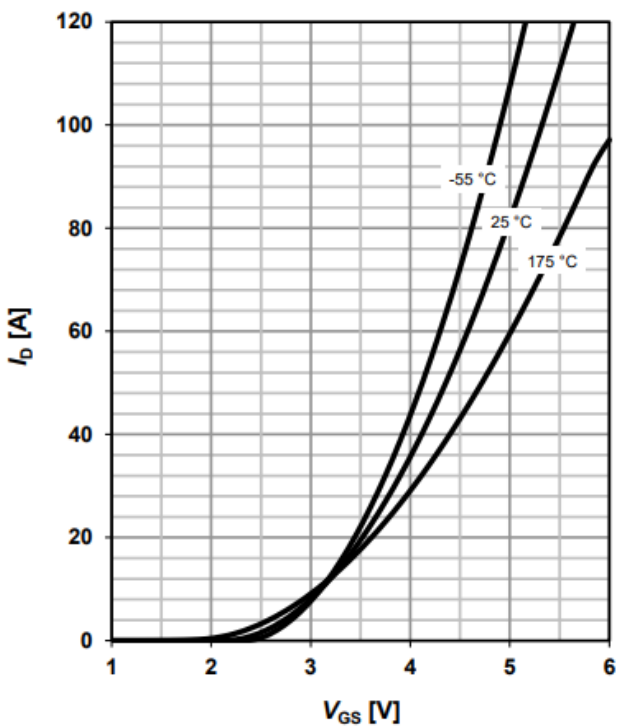
parameter: V_{GS}



7 典型转移特性

$$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$$

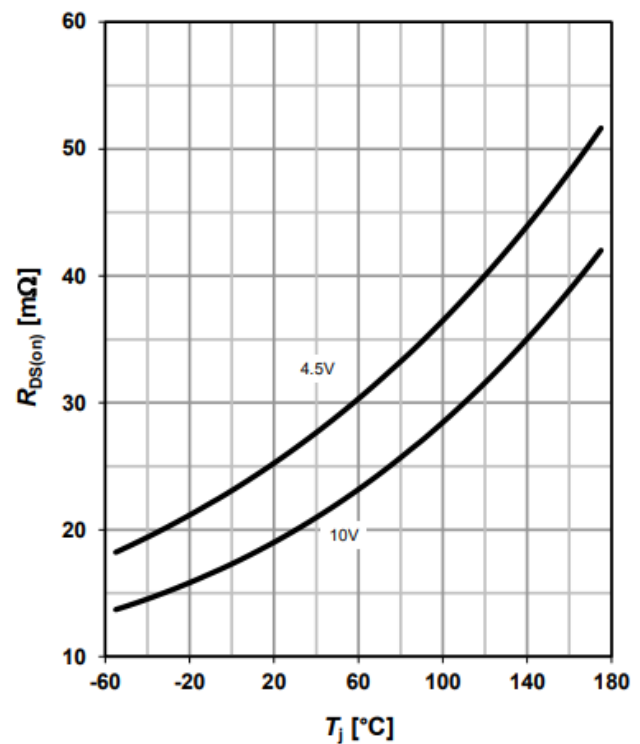
parameter: T_j



8 典型漏源导通电阻

$$R_{DS(on)} = f(T_j); I_D = 15\text{ A}$$

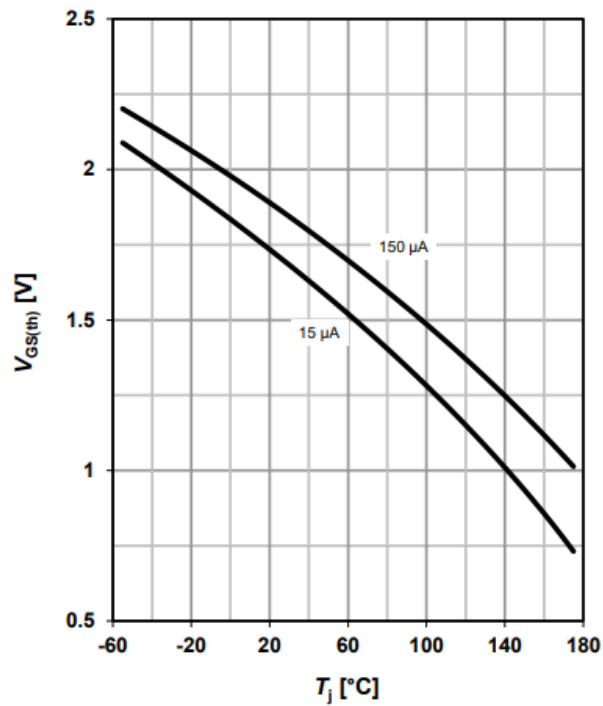
parameter: V_{GS}



9 典型栅极阈值电压

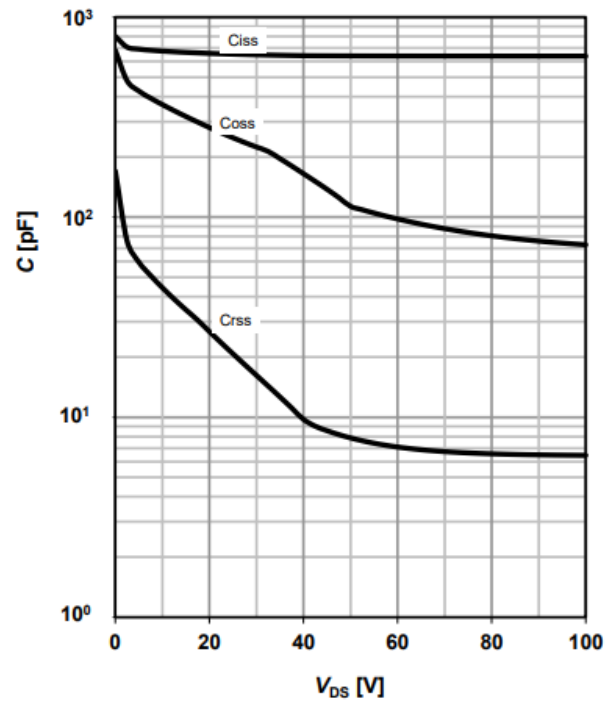
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter: I_D



10 典型电容值

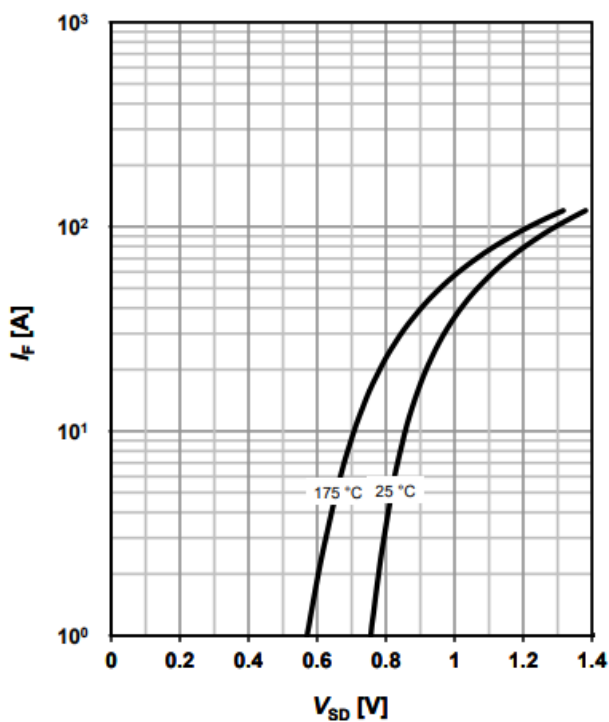
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$



11 典型二极管正向导通特性

$$I_F = f(V_{SD})$$

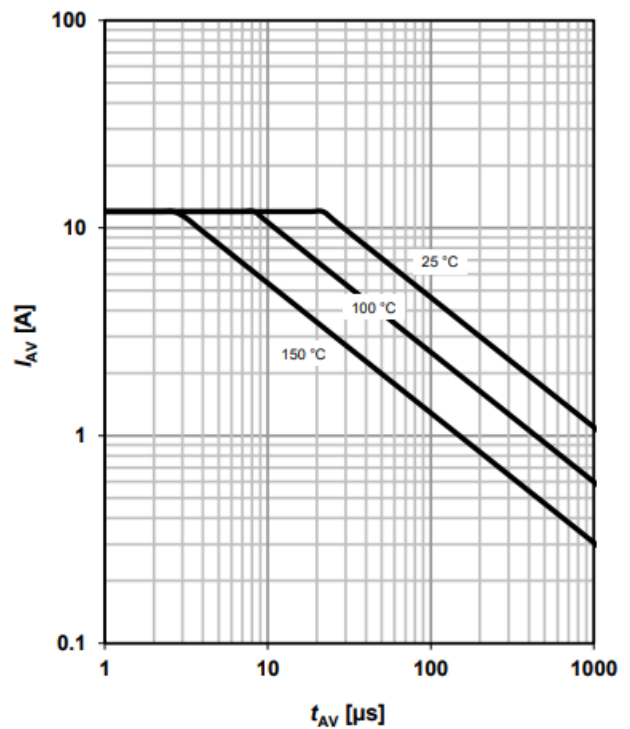
parameter: T_j



12 典型雪崩特性

$$I_{AS} = f(t_{AV})$$

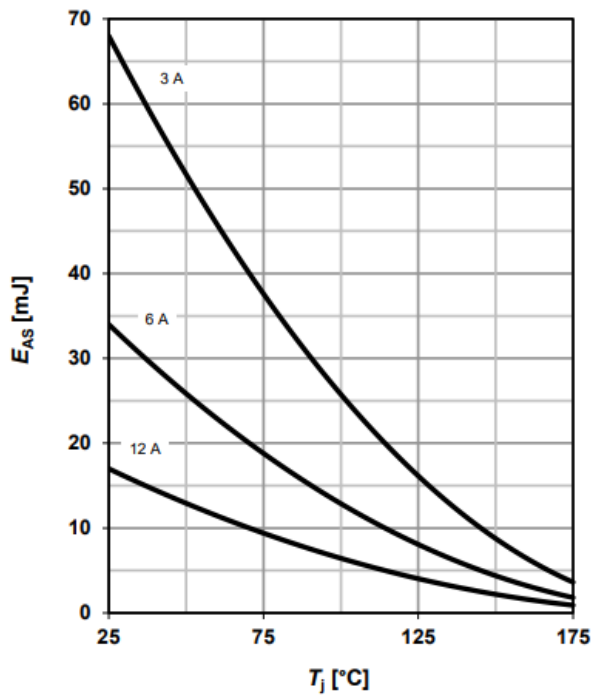
parameter: $T_{j(start)}$



13 典型雪崩能量

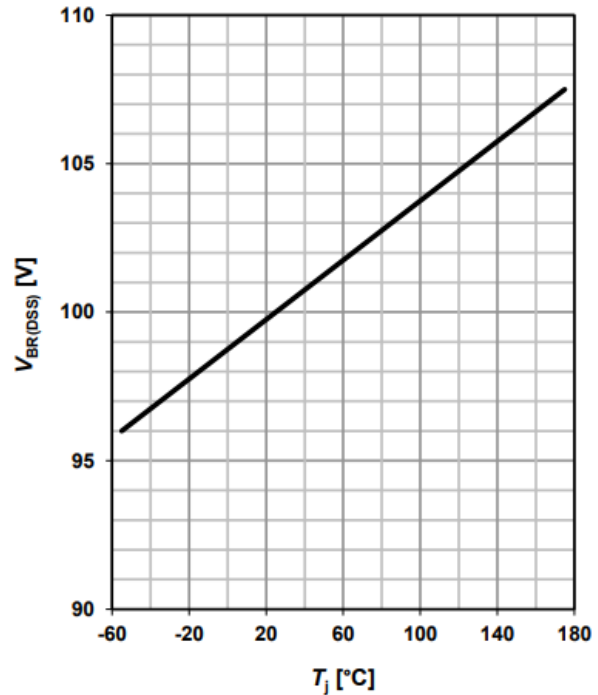
$$E_{AS} = f(T_j)$$

parameter: I_D



14 漏源击穿电压

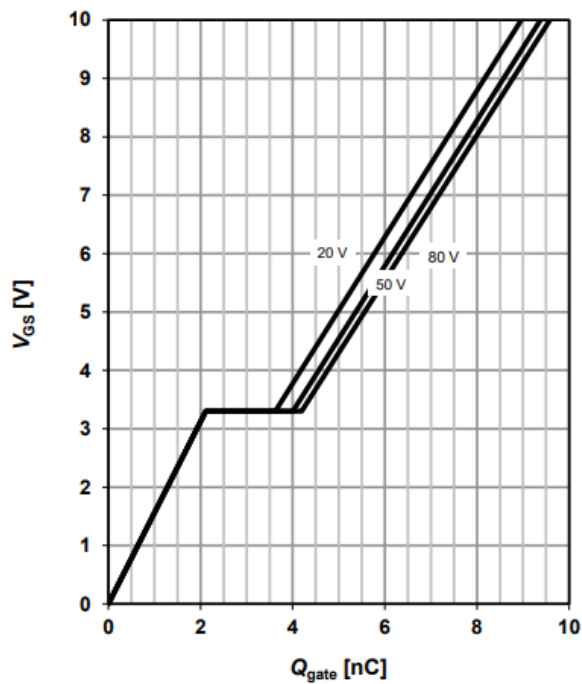
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



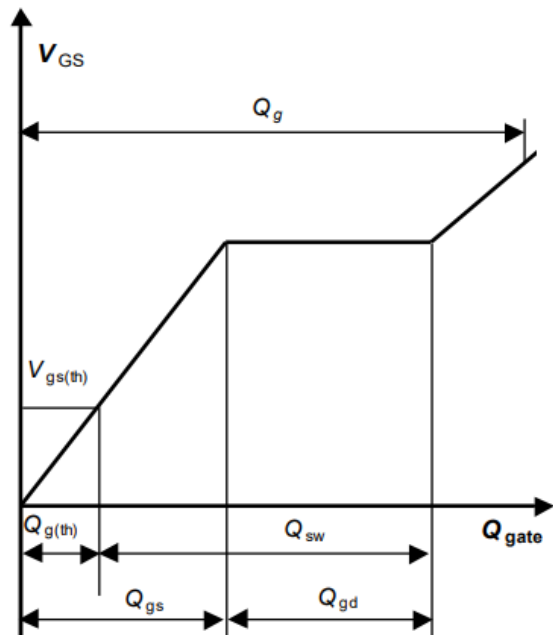
15 典型栅极电荷

$$V_{GS} = f(Q_{gate}); I_D = 15 \text{ A pulsed}$$

parameter: V_{DD}



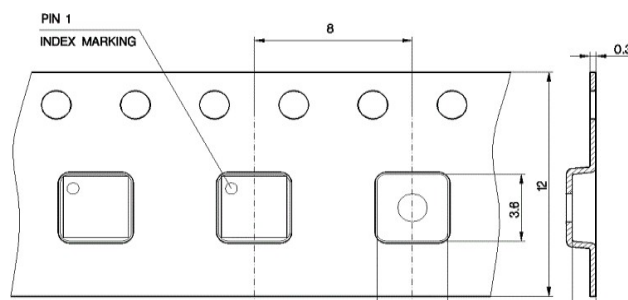
16 栅极充电波形



[illegible]

Figure 1: Dimensions of the PCB layout. The figure consists of two parts: (a) Top view and (b) Side view. Part (a) shows a top view of the PCB with dimensions in inches. The overall dimensions are 2.29 inches by 2.36 inches. The layout includes a central copper area with a width of 0.65 inches and a length of 0.34 inches. There are also smaller copper areas with dimensions 0.34, 0.65, and 0.34. The solder mask has a thickness of 0.005 inches. The stencil apertures have a thickness of 0.005 inches. Part (b) shows a side view of the PCB with dimensions in inches. The overall dimensions are 0.475 inches by 1.22 inches. The layout includes a central copper area with a width of 0.35 inches and a length of 0.35 inches. There are also smaller copper areas with dimensions 0.35, 0.35, and 0.35. The solder mask has a thickness of 0.005 inches. The stencil apertures have a thickness of 0.005 inches.

包装信息



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Revision History

Version	Date	Changes
Revision 1.0	23.07.2019	Final Data Sheet



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